

2SK1957 Silicon N Channel MOS FET

REJ03G0988-0200 (Previous: ADE-208-1336) Rev.2.00 Sep 07, 2005

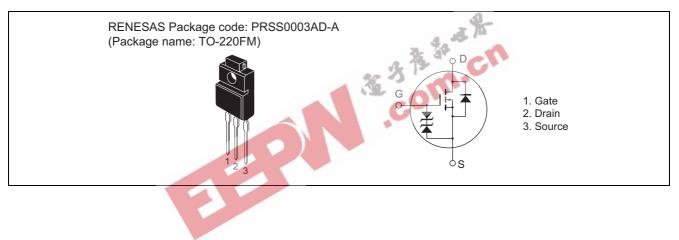
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter, motor control

Outline





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
ltem	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	200	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	7	А
Drain peak current	I _{D(pulse)} * ¹	28	А
Body to drain diode reverse drain current	I _{DR}	7	А
Channel dissipation	Pch* ²	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	–55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = $25^{\circ}C$

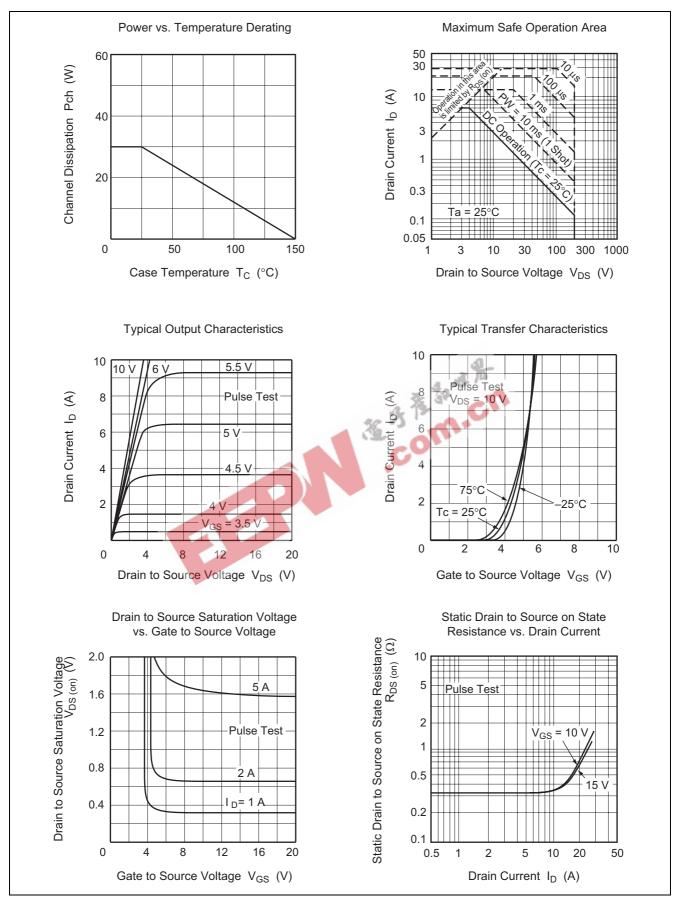
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
ltem	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	200	—	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±20	—	—	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}		—	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	—	250	μA	$V_{DS} = 160 V, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	2.0	—	4.0	V	I _D = 1 mA, V _{DS} = 10 V
Static drain to source on state	R _{DS(on)}	_	0.33	0.45	Ω	$I_D = 4 \text{ A}, \text{ V}_{GS} = 10 \text{ V}^{*3}$
resistance			36	3		
Forward transfer admittance	y _{fs}	3.0	4.5	-O'	S	$I_D = 4 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss		700	6	pF	$V_{DS} = 10 V, V_{GS} = 0,$
Output capacitance	Coss		260	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	77	45	—	pF	
Turn-on delay time	t _{d(on)}		20	—	ns	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	tr	_	45	—	ns	R _L = 7.5 Ω
Turn-off delay time	t _{d(off)}	_	50	—	ns	
Fall time	t _f	_	35	—	ns	
Body to drain diode forward voltage	V _{DF}	_	1.1	—	V	$I_F = 7 \text{ A}, V_{GS} = 0$
Body to drain diode reverse	t _{rr}	_	150	—	ns	$I_F = 7 \text{ A}, V_{GS} = 0,$
recovery time						di _F /dt = 100 A/µs

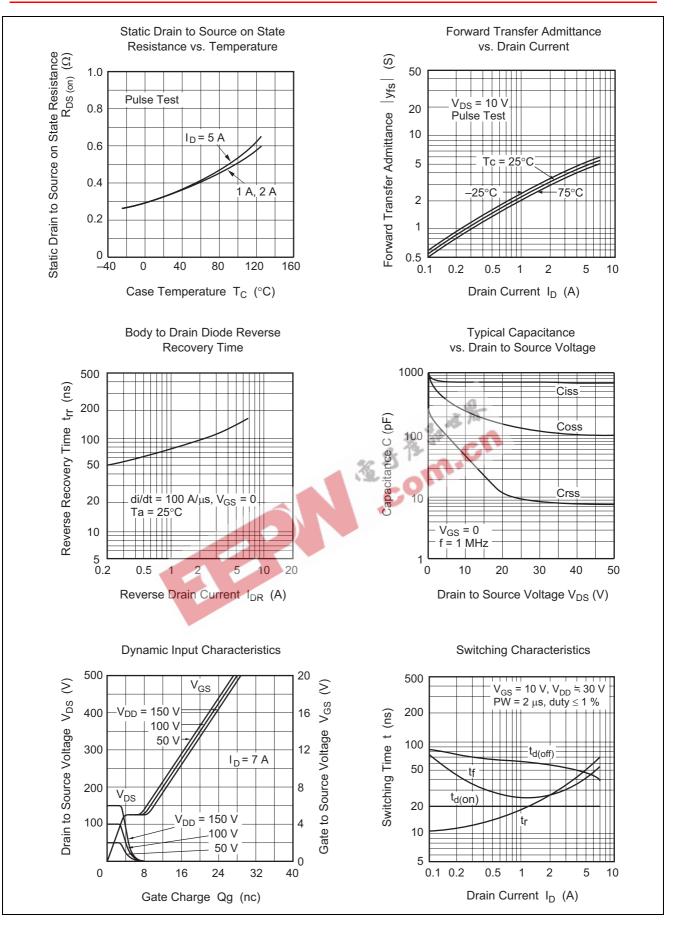
Note: 3. Pulse Test



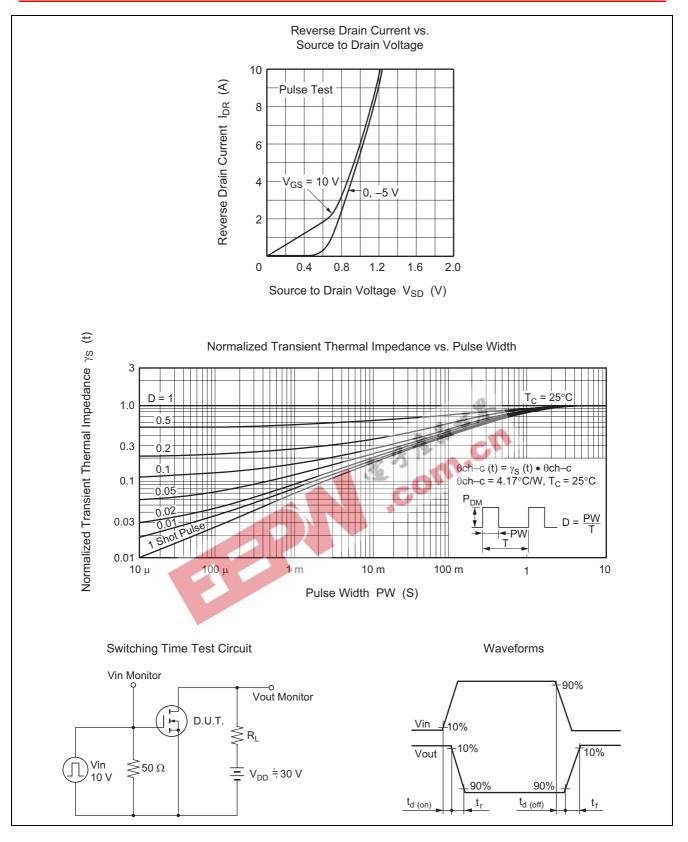
Main Characteristics





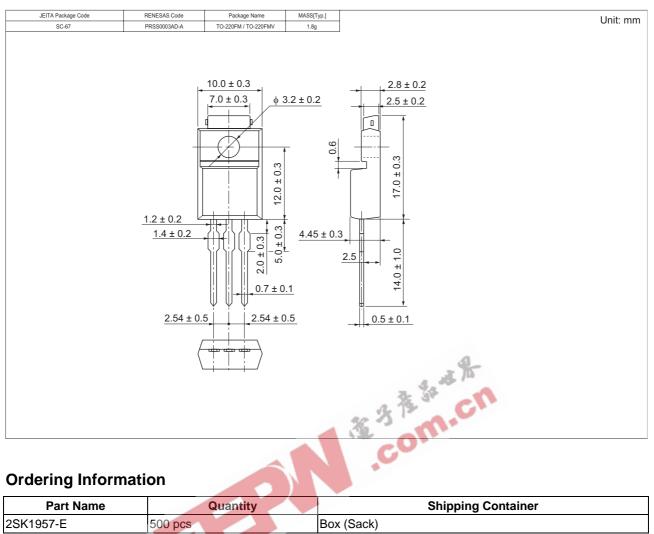








Package Dimensions



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